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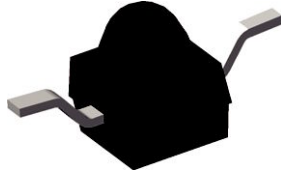




## Silicon PIN Photodiode



21568-1 VEMD2020X01



VEMD2000X01

### DESCRIPTION

VEMD2000X01 and VEMD2020X01 are high speed and high sensitive PIN photodiodes in a miniature surface mount package (SMD) with dome lens and daylight blocking filter. Filter is matched with IR emitters operating at wavelength of 830 nm to 950 nm. The photo sensitive area of the chip is 0.23 mm<sup>2</sup>.

### FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- High radiant sensitivity
- Daylight blocking filter matched with 830 nm to 950 nm IR emitters
- Fast response times
- Angle of half sensitivity:  $\phi = \pm 15^\circ$
- Package matched with IR emitter series VSMB2000X01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



### Note

\*\* Please see document "Vishay Material Category Policy": [www.vishay.com/doc?99902](http://www.vishay.com/doc?99902)

### APPLICATIONS

- High speed photo detector
- Infrared remote control
- Infrared data transmission
- Photo interrupters
- Shaft encoders

| PRODUCT SUMMARY |                      |         |                       |
|-----------------|----------------------|---------|-----------------------|
| COMPONENT       | I <sub>ra</sub> (μA) | φ (deg) | λ <sub>0.5</sub> (nm) |
| VEMD2000X01     | 12                   | ± 15    | 750 to 1050           |
| VEMD2020X01     | 12                   | ± 15    | 750 to 1050           |

### Note

- Test conditions see table "Basic Characteristics"

| ORDERING INFORMATION |               |                              |                  |
|----------------------|---------------|------------------------------|------------------|
| ORDERING CODE        | PACKAGING     | REMARKS                      | PACKAGE FORM     |
| VEMD2000X01          | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Reverse gullwing |
| VEMD2020X01          | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Gullwing         |

### Note

- MOQ: minimum order quantity

| ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified) |                                   |                   |               |      |
|---------------------------------------------------------------------------------|-----------------------------------|-------------------|---------------|------|
| PARAMETER                                                                       | TEST CONDITION                    | SYMBOL            | VALUE         | UNIT |
| Reverse voltage                                                                 |                                   | V <sub>R</sub>    | 60            | V    |
| Power dissipation                                                               | T <sub>amb</sub> ≤ 25 °C          | P <sub>V</sub>    | 215           | mW   |
| Junction temperature                                                            |                                   | T <sub>j</sub>    | 100           | °C   |
| Operating temperature range                                                     |                                   | T <sub>amb</sub>  | - 40 to + 100 | °C   |
| Storage temperature range                                                       |                                   | T <sub>stg</sub>  | - 40 to + 100 | °C   |
| Soldering temperature                                                           | Acc. reflow solder profile fig. 7 | T <sub>sd</sub>   | 260           | °C   |
| Thermal resistance junction/ambient                                             | Acc. J-STD-051                    | R <sub>thJA</sub> | 250           | K/W  |



| <b>BASIC CHARACTERISTICS</b> ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified) |                                                                               |                 |      |             |      |               |
|-----------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------|-----------------|------|-------------|------|---------------|
| PARAMETER                                                                                           | TEST CONDITION                                                                | SYMBOL          | MIN. | TYP.        | MAX. | UNIT          |
| Forward voltage                                                                                     | $I_F = 50\text{ mA}$                                                          | $V_F$           |      | 1           |      | V             |
| Breakdown voltage                                                                                   | $I_R = 100\text{ }\mu\text{A}$ , $E = 0$                                      | $V_{(BR)}$      | 32   |             |      | V             |
| Reverse dark current                                                                                | $V_R = 10\text{ V}$ , $E = 0$                                                 | $I_{ro}$        |      | 1           | 10   | nA            |
| Diode capacitance                                                                                   | $V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$                             | $C_D$           |      | 4           |      | pF            |
|                                                                                                     | $V_R = 5\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$                             | $C_D$           |      | 1.3         |      | pF            |
| Open circuit voltage                                                                                | $E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$                          | $V_o$           |      | 350         |      | mV            |
| Temperature coefficient of $V_o$                                                                    | $E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$                          | $TK_{V_o}$      |      | -2.6        |      | mV/K          |
| Short circuit current                                                                               | $E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$                          | $I_k$           |      | 11          |      | $\mu\text{A}$ |
| Temperature coefficient of $I_k$                                                                    | $E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$                          | $TK_{I_k}$      |      | 0.1         |      | %/K           |
| Reverse light current                                                                               | $E_e = 1\text{ mW/cm}^2$ , $\lambda = 950\text{ nm}$ ,<br>$V_R = 5\text{ V}$  | $I_{ra}$        | 8.5  | 12          | 17   | $\mu\text{A}$ |
| Angle of half sensitivity                                                                           |                                                                               | $\phi$          |      | $\pm 15$    |      | deg           |
| Wavelength of peak sensitivity                                                                      |                                                                               | $\lambda_p$     |      | 940         |      | nm            |
| Range of spectral bandwidth                                                                         |                                                                               | $\lambda_{0.5}$ |      | 750 to 1050 |      | nm            |
| Rise time                                                                                           | $V_R = 10\text{ V}$ , $R_L = 1\text{ k}\Omega$ ,<br>$\lambda = 820\text{ nm}$ | $t_r$           |      | 100         |      | ns            |
| Fall time                                                                                           | $V_R = 10\text{ V}$ , $R_L = 1\text{ k}\Omega$ ,<br>$\lambda = 820\text{ nm}$ | $t_f$           |      | 100         |      | ns            |

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

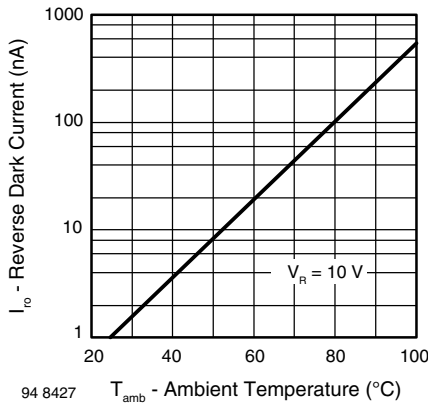


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

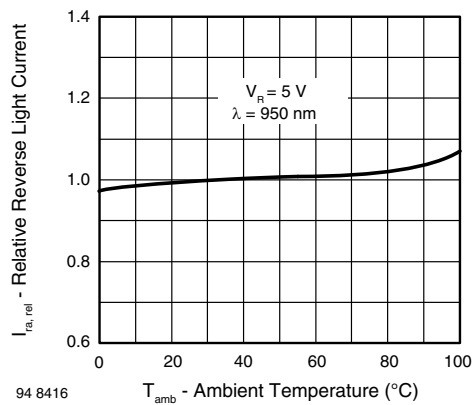


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature



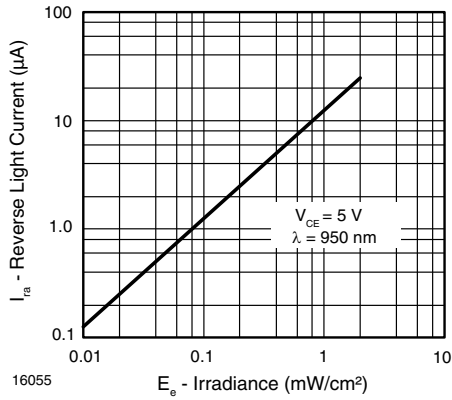


Fig. 3 - Reverse Light Current vs. Irradiance

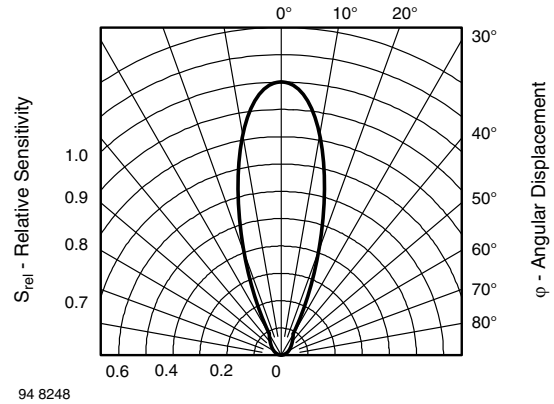


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

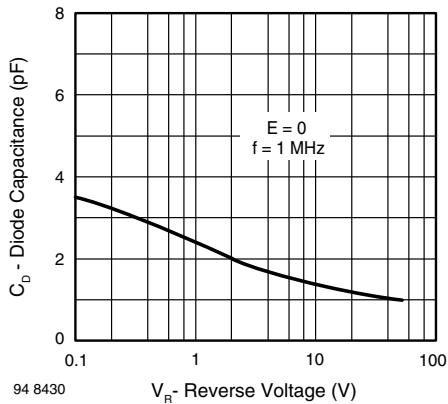


Fig. 4 - Diode Capacitance vs. Reverse Voltage

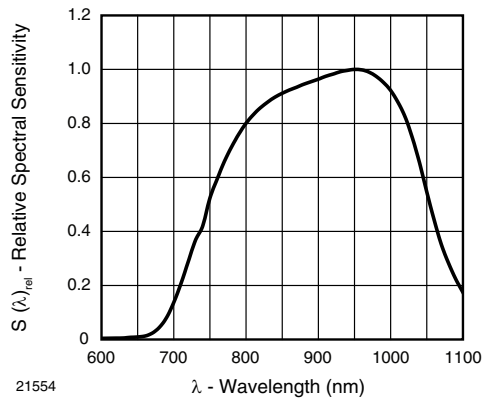


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength



## REFLOW SOLDER PROFILE

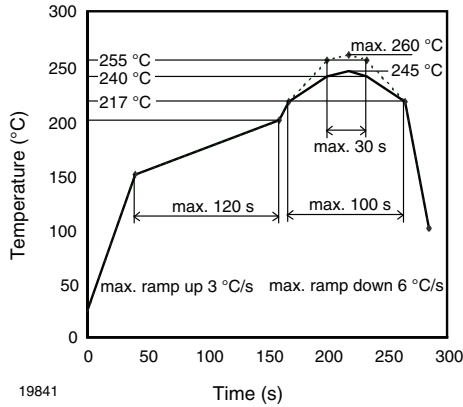


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb} < 30\text{ °C}$ ,  $RH < 60\%$

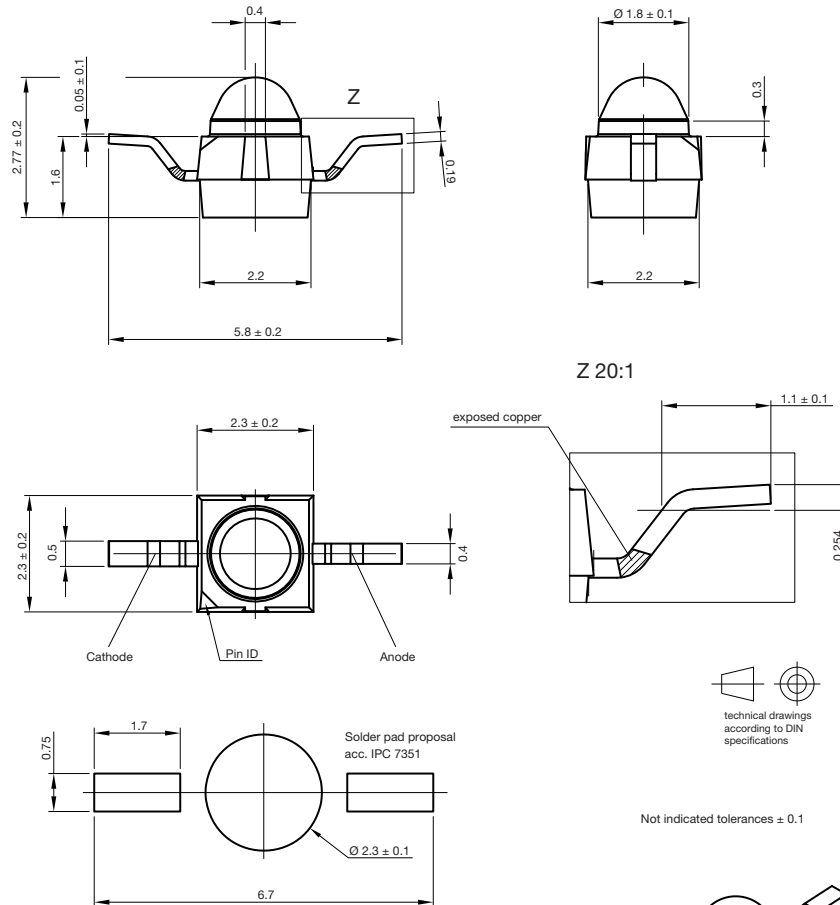
Moisture sensitivity level 2a, acc. to J-STD-020.

## DRYING

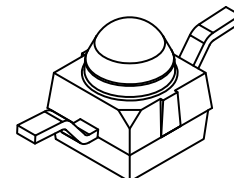
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label.

Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C),  $RH < 5\%$ .

## PACKAGE DIMENSIONS in millimeters: VEMD2000

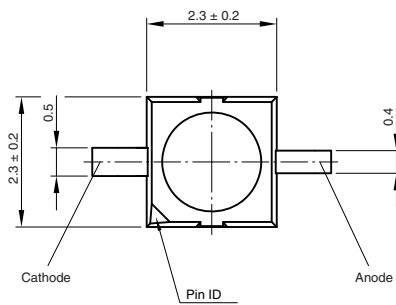
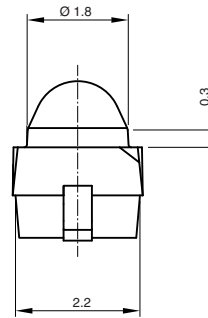
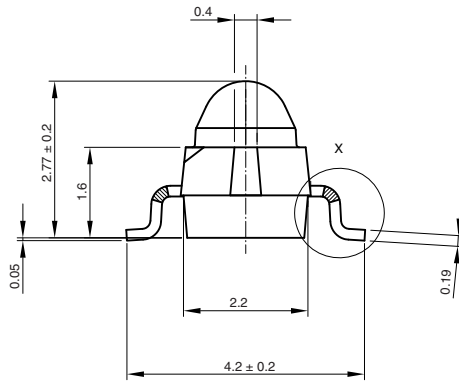


Drawing-No.: 6.544-5391.02-4  
Issue: 2; 18.03.10  
21517

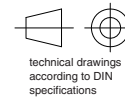
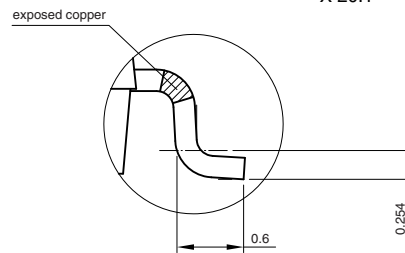




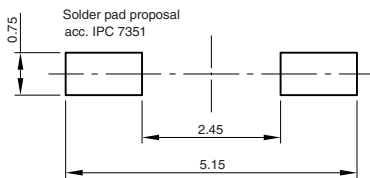
## PACKAGE DIMENSIONS in millimeters: VEMD2020



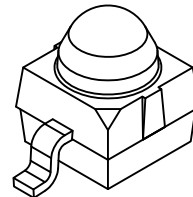
X 20:1



technical drawings according to DIN specifications



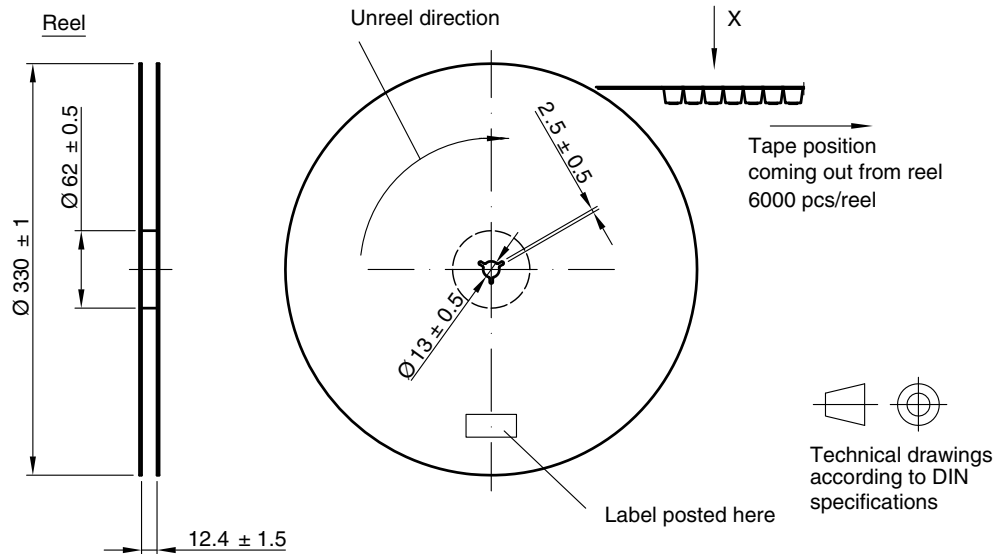
Not indicated tolerances ± 0.1



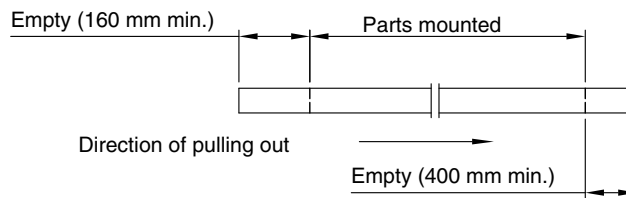
Drawing-No.: 6.544-5383.02-4  
Issue: 4; 18.03.10  
21488



**TAPING AND REEL DIMENSIONS** in millimeters: **VEMD2000**

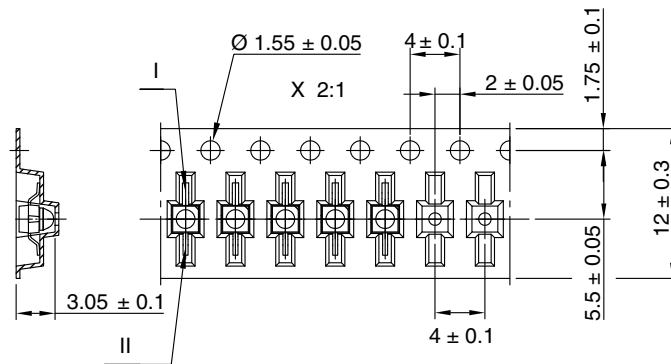


Leader and trailer tape:



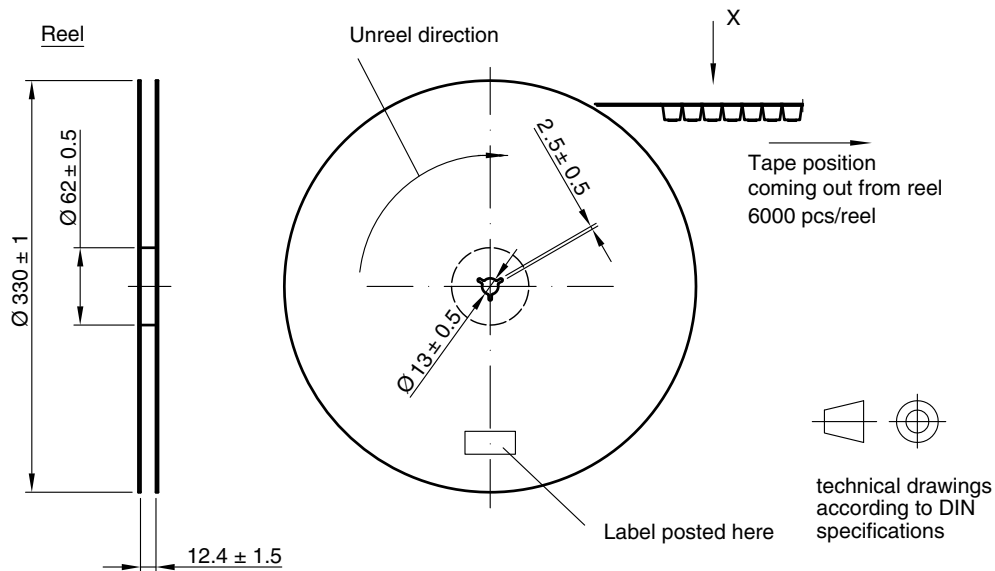
Terminal position in tape

| Device     | Lead I    | Lead II |
|------------|-----------|---------|
| VEMT2000   | Collector | Emitter |
| VEMD2000   |           |         |
| VEMD2500   | Cathode   | Anode   |
| VSMB2000   |           |         |
| VSMG2000   |           |         |
| VSMY2850RG | Anode     | Cathode |

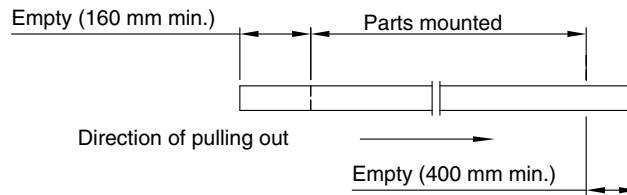


Drawing-No.: 9.800-5100.01-4  
 Issue: 2; 18.03.10  
 21572

## TAPING AND REEL DIMENSIONS in millimeters: VEMD2020

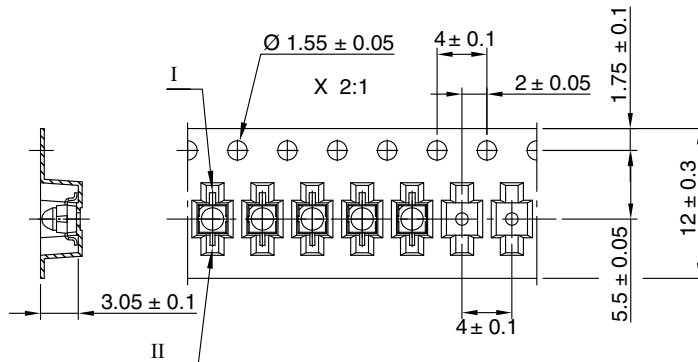


### Leader and trailer tape:



### Terminal position in tape

| Device    | Lead I    | Lead II |
|-----------|-----------|---------|
| VEMT2020  | Collector | Emitter |
| VEMT2520  |           |         |
| VSMB2020  | Cathode   | Anode   |
| VSMG2020  |           |         |
| VEMD2020  |           |         |
| VEMD2520  | Anode     | Cathode |
| VSMY2850G |           |         |



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

21571





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